



PATENT

I hereby certify that on the date specified below, this correspondence is being deposited with the United States Postal Service as first-class mail in an envelope addressed to Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

July 8, 2005  
Date

Carolyn L. Ross  
Carolyn L. Ross

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Appl. No. : 10/801,386

Confirmation No. : 3160

Applicant : Tongbi Jiang

Filed : March 15, 2004

Attorney Docket No.: 500180.03

Art Unit : 2814

Customer No. : 27,076

Examiner : Wai Sing Louie

Title : PRESSURE AND HEAT CURED SEMICONDUCTOR DIE PACKAGES HAVING  
REDUCED VOIDS IN A DIE ATTACH BONDLINE

*Fee  
Only*

**RESPONSE TO RESTRICTION REQUIREMENT**

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

In response to the Restriction Requirement dated May 4, 2005, please extend the period of time for response two months, to expire on August 4, 2005. Enclosed is the requisite fee.

Listing of the Claims begins on page 2 of this paper.

Remarks begin on page 5 of this paper.

7/11/05 10:00 AM 370.00 DA 100.00 DA